## Abstract

A module device with mounted components with no damage in reliability. This device has a board with metallized connection electrodes and components mounted on the board by arrangement in the longitudinal direction of the board, and each connected to the connection electrode via a bump. Bumps for connecting the components to the board connection electrodes are so set that their height may increase toward the side of the board with the reference of the height of the bump located at the center region in the longitudinal direction of the board.